

Indium Arsenide

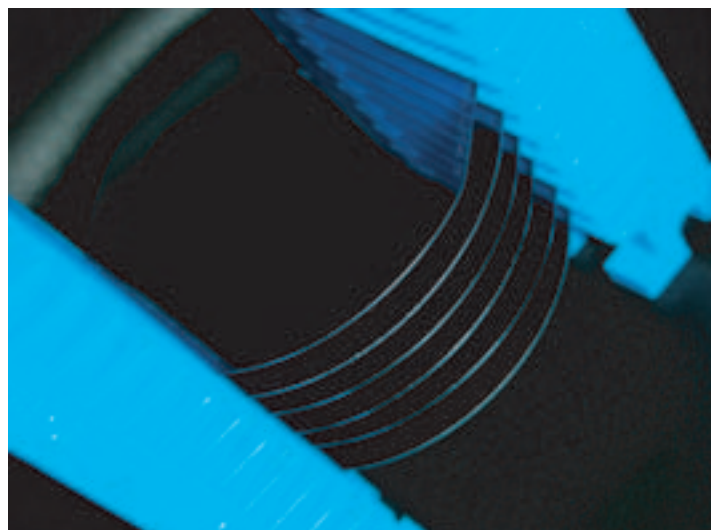
Epitaxy Ready Polished Wafers



Wafer Technology offers single crystals that are grown in a high pressure liquid encapsulated Czochralski process using at least 99.9999% (6N) pure indium and arsenic in pure fused silica crucibles

Mechanical Specifications

Indium arsenide can be supplied as ingots sections, as-cut, etched or polished wafers. All Indium Arsenide wafers are individually laser scribed with ingot and slice identity to ensure perfect traceability



Packaging

Polished Wafers

Fluoroware type tray, individually sealed in two outer bags in inert atmosphere

As-cut Wafers

Fluoroware type tray or glassine bag

'Process Trial' wafers

Fluoroware type tray, individually sealed in one outer bag

If you do not see the specification you require, please ask for details



WAFER TECHNOLOGY LTD

WAFER SPECIFICATIONS

	2" diameter slices	3" diameter slices
Orientation	(100)±0.1°	(100)±0.1°
	Misorientations up to 10° in any direction are available. For other orientations and directions please ask.	
Diameter	50.5±0.5mm	76.2±0.4mm
Flat Option	EJ	EJ
Flat orientation tolerance	±0.1°	±0.1°
	Wafers can also be supplied with either the major or minor flat prepared to an orientation tolerance of 0.02°.	
Major flat length	16±2mm	22±2mm
Minor flat length	8±1mm	11±1mm
Thickness/μm	500±25μm	625±25μm
Lasermark	Back surface parallel to the major flat	

ELECTRONIC AND CRYSTALLOGRAPHIC SPECIFICATIONS

Dopant	Type	Carrier Concentration cm ⁻³	Mobility cm ² V ⁻¹ s ⁻¹	E.P.D. cm ²
Undoped	n-type	(1-3)×10 ¹⁶	≥23000	2"≤15000 3"≤50000
Low Sulphur	n-type	(4-8)×10 ¹⁶	25000-15000	
High Sulphur	n-type	(1-3)×10 ¹⁸	12000-7000	
Low Zinc	p-type	(1-3)×10 ¹⁷	350-200	
High Zinc	p-type	(1-3)×10 ¹⁸	250-100	

Tighter electrical ranges are available on request

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For all your III-V needs

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